

Sequential Linear LED Driver

Features

- ▶ Minimal component count
(base config: CL8801 + 4 resistors + diode bridge)
- ▶ No magnetics, no capacitors
- ▶ Up to 13W output
- ▶ >115lm/W using efficient LEDs
- ▶ 85 - 90% electrical efficiency
- ▶ > 0.9 power factor
- ▶ < 30% THD line current
- ▶ Low conducted EMI w/o filters
- ▶ 80–90% LED utilization
- ▶ Phase dimmer compatible with an RC network

Applications

- ▶ Fluorescent tube retrofit
- ▶ Incandescent & CFL bulb replacement
- ▶ General LED lighting

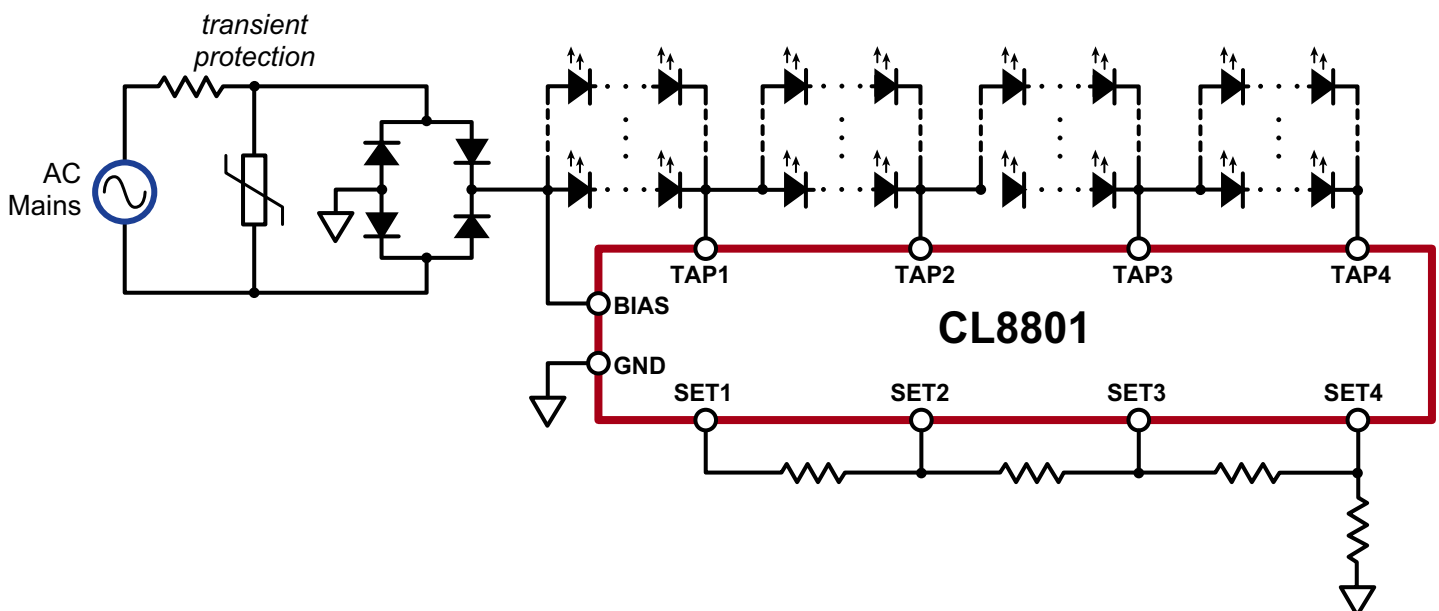
General Description

The CL8801 is designed to drive a long string of inexpensive, low current LEDs directly from the AC mains. A basic driver circuit consists of the CL8801, four resistors, and a bridge rectifier. Two to four additional components are optional for various levels of transient protection. No capacitors, EMI filters, or power factor correction circuits are needed.

A string of series/parallel LEDs is tapped at four locations. Four linear current regulators sink current at each tap and are sequentially turned on and off, tracking the input sine wave voltage. Voltage across each regulator is minimized when conducting, providing high efficiency. Output current at each tap is individually resistor-adjustable. Cross-regulation, as the CL8801 switches from one regulator to the next, provides smooth transitions. The current waveform can be tailored to optimize for input voltage range, line/load regulation, output power/current, efficiency, power factor, THD, dimmer compatibility, and LED utilization.

With the addition of an RC network, the driver is compatible with phase dimming.

Typical Application Circuit



Ordering Information

Part Number	Package Options	Packing
CL8801K6-G	40-Lead (6x6) QFN	490/Tray
CL8801K6-G M935	40-Lead (6x6) QFN	2000/Reel
CL8801K63-G	33-Lead (6x6) QFN*	490/Tray
CL8801K63-G M935	33-Lead (6x6) QFN*	2000/Reel

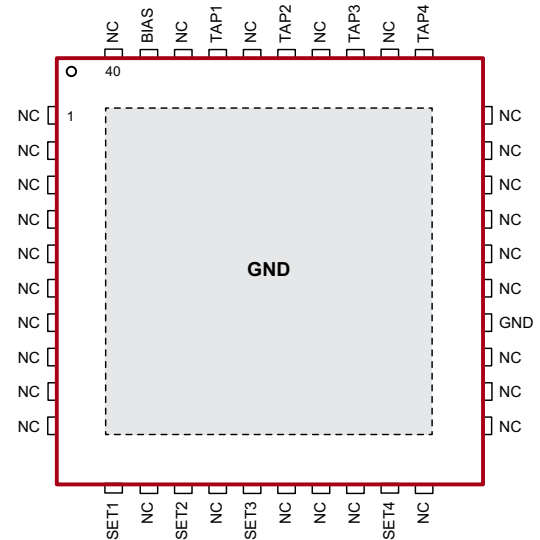
- G indicates package is RoHS compliant ('Green')

* Consult factory for package option availability

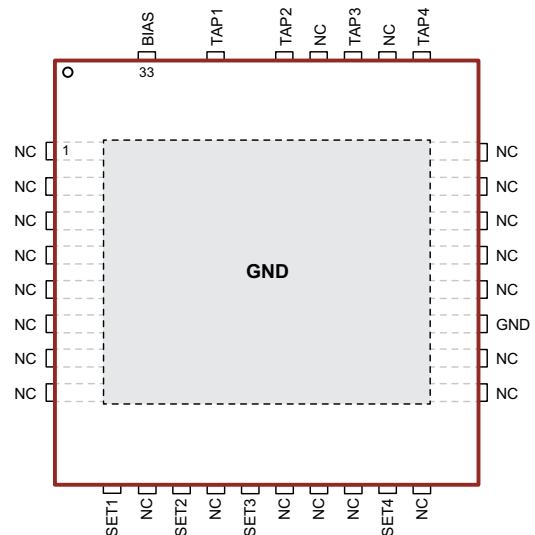


ESD Sensitive Device

Pin Configuration



40-Lead QFN (K6)
(top view)



33-Lead QFN (K6)
(top view)

Absolute Maximum Ratings

Parameter	Value
V_{BIAS}, V_{TAP1}	-0.5V to +550V
V_{TAP2-4}	-0.5V to +320V
V_{SET1-4}	4.0V
Operating junction temperature	-40°C to +125°C
Storage temperature, T_s	-65°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Typical Thermal Resistance

Package	θ_{ja}
40-Lead QFN	24°C/W
33-Lead QFN	24°C/W

Note:

1. Mounted to an exposed 1oz PCB copper area of 4.0cm².

Product Marking

CL8801
LLLLLL
YYWW
AAACCC

L = Lot Number
YY = Year Sealed
WW = Week Sealed
A = Assembler ID
C = Country of Origin
— = "Green" Packaging

40-Lead QFN (K6)

CL8801
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33-Lead QFN (K6)

Note:

The CL8801 will initially be offered in a 40-lead package and will switch to the 33-lead package when available. Printed circuit boards should be laid out for the 33-lead package.

Recommended Operating Conditions

Sym	Parameter		Min	Typ	Max	Units	Conditions
I_{OUT}	Output current	TAP1	-	-	40	mA	---
		TAP2	-	-	90		
		TAP3	-	-	200		
		TAP4	-	-	200		
V_{OUT}	Output voltage	TAP1	-	-	400	V	Non-conducting
		TAP2-4	-	-	300		Non-conducting
		TAP1-4	-	-	(1)		Conducting
V_{BIAS}	Applied BIAS voltage		-	-	440	V	---

Note:

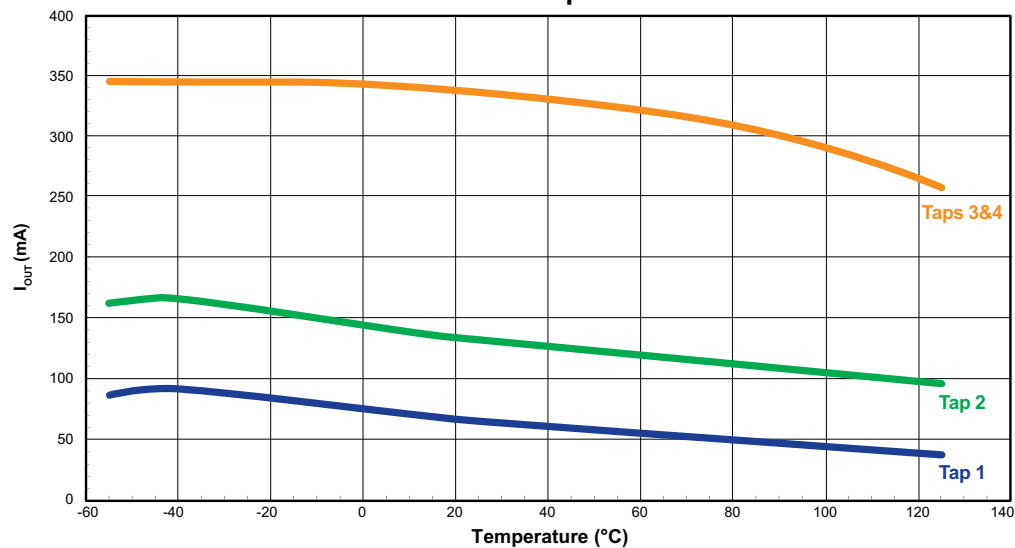
(1) Voltage capability is determined by power dissipation ($V \times I$).

Electrical Characteristics (over recommended operating conditions at 25°C unless specified otherwise)

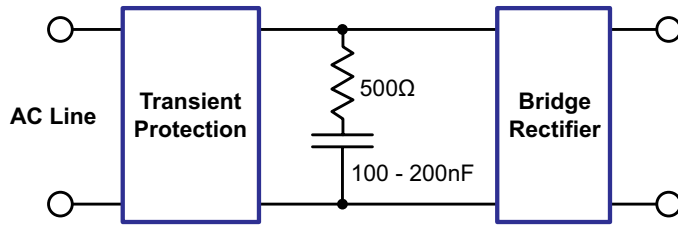
Sym	Parameter		Min	Typ	Max	Units	Conditions
I_{BIAS}	BIAS pin input current		-	250	410	μA	$V_{BIAS} = 170V$
$I_{TAP(ON)}$	Output current, on	TAP1	40	-	-	mA	$V_{TAP1} = 30V, V_{SET1-4} = GND$
		TAP2	90	-	-		$V_{TAP2} = 17V, V_{SET1-4} = GND$
		TAP3	200	-	-		$V_{TAP3} = 17V, V_{SET1-4} = GND$
		TAP4	200	-	-		$V_{TAP4} = 17V, V_{SET1-4} = GND$
$I_{TAP(OFF)}$	Output current, off		-	0	10	μA	TAP1 - 4, $V_{BIAS} = 170V$
V_{REG}	Regulation voltage at SET pins	SET1 - 3	1.80	2.00	2.20	V	---
		SET4	1.89	2.10	2.31		

Output Current Thermal Characteristics

Maximum Output Current

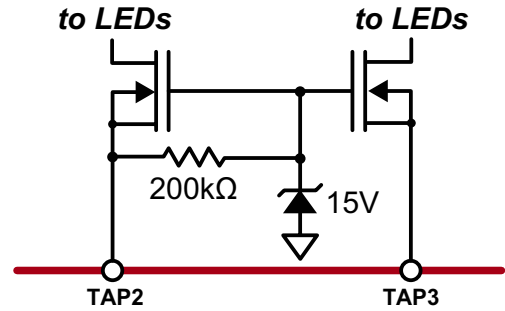


Less common is inadequate holding current. The minimum dimming holding current is typically 10-20mA. Tap1 at 40mA (max) exceeds the minimum.



Power Boost

Higher output power can be achieved by off-loading a portion of the power dissipation from the CL8801 to external FETs. The circuit below drops most of the tap voltage across the FETs, thereby shifting the bulk of the dissipation to the FET.

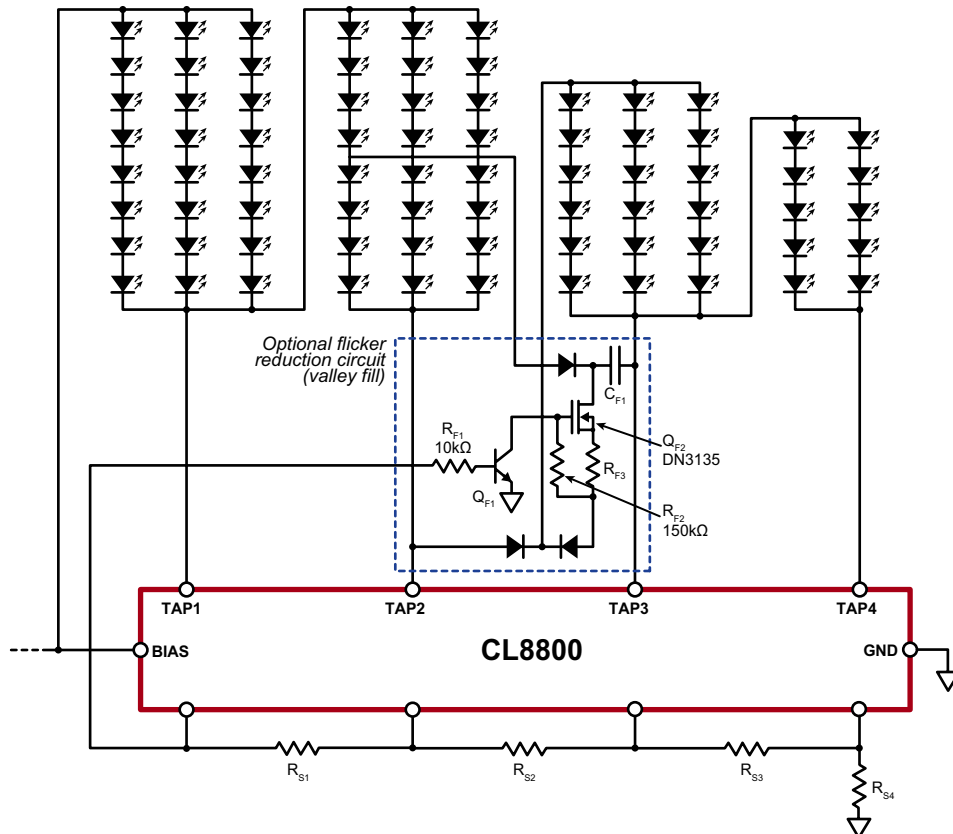


Flicker

Twice per AC line cycle the line voltage crosses zero volts, during which time there is no light output.

The circuit below can provide 5-10% valley fill. It has little effect on input current waveshape (THD, PF) and efficiency.

Valley Fill Circuit



Pin Description (40-Lead K6)

Pin #	Pin Name	Description
1 - 10	NC	No internal connection (use for heat sink ground plane pass through).
11	SET1	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
12	NC	No internal connection.
13	SET2	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
14	NC	No internal connection.
15	SET3	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
16	NC	No internal connection.
17	NC	No internal connection.
18	NC	No internal connection.
19	SET4	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
20	NC	No internal connection.
21 - 23	NC	No internal connection (use for heat sink ground plane pass through).
24	GND	Circuit common. Connect to bridge rectifier return (use for heat sink ground plane pass through).
25 - 30	NC	No internal connection (use for heat sink ground plane pass through).
31	TAP4	Current regulator outputs. Connect to taps along the LED string.
32	NC	No internal connection.
33	TAP3	Current regulator outputs. Connect to taps along the LED string.
34	NC	No internal connection.
35	TAP2	Current regulator outputs. Connect to taps along the LED string.
36	NC	No internal connection.
37	TAP1	Current regulator outputs. Connect to taps along the LED string.
38	NC	No internal connection.
39	BIAS	Provides bias for driver. Connect to rectified AC.
40	NC	No internal connection.
Underside plate (GND)		For heatsinking purposes, it should be soldered to a 4.0cm ² exposed copper area. It should also be electrically connected to circuit common (GND).

Note:

The high voltage pins are located on one side of the package and are arranged from lowest voltage to highest. Pin-to-pin voltage gradients are minimized.

Pin Description (33-Lead K6)

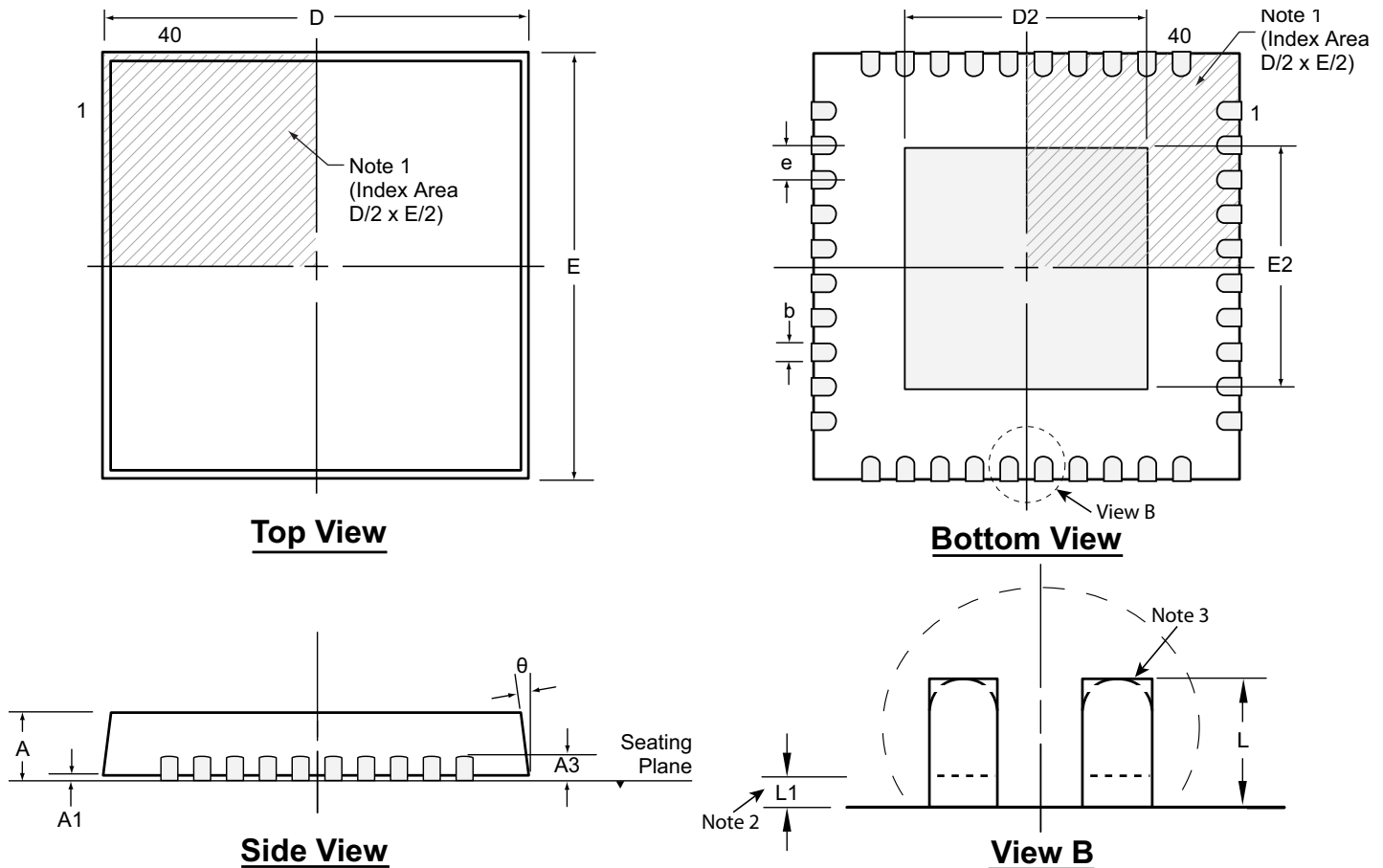
Pin #	Pin Name	Description
1 - 8	NC	No internal connection.
9	SET1	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
10	NC	No internal connection.
11	SET2	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
12	NC	No internal connection.
13	SET3	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
14	NC	No internal connection.
15	NC	No internal connection.
16	NC	No internal connection.
17	SET4	Current sense for linear current regulators for each tap. Resistors on these pins sets the tap currents.
18	NC	No internal connection.
19 - 20	NC	No internal connection.
21	GND	Circuit common. Connect to bridge rectifier return (use for heat sink ground plane pass through).
22 - 26	NC	No internal connection.
27	TAP4	Current regulator outputs. Connect to taps along the LED string.
28	NC	No internal connection.
29	TAP3	Current regulator outputs. Connect to taps along the LED string.
30	NC	No internal connection.
31	TAP2	Current regulator outputs. Connect to taps along the LED string.
32	TAP1	Current regulator outputs. Connect to taps along the LED string.
33	BIAS	Provides bias for driver. Connect to rectified AC.
Underside plate (GND)		For heatsinking purposes, it should be soldered to a 4.0cm ² exposed copper area. It should also be electrically connected to circuit common (GND).

Note:

The high voltage pins are located on one side of the package and are arranged from lowest voltage to highest. Pin-to-pin voltage gradients are minimized.

40-Lead QFN Package Outline (K6)

6.00x6.00mm body, 1.00mm height (max), 0.50mm pitch



Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Depending on the method of manufacturing, a maximum of 0.15mm pullback ($L1$) may be present.
3. The inner tip of the lead may be either rounded or square.

Symbol		A	A1	A3	b	D	D2	E	E2	e	L	L1	θ°
Dimension (mm)	MIN	0.80	0.00	0.20 REF	0.18	5.85*	1.05	5.85*	1.05	0.50 BSC	0.30 [†]	0.00	0
	NOM	0.90	0.02		0.25	6.00	-	6.00	-		0.40 [†]	-	-
	MAX	1.00	0.05		0.30	6.15*	4.45	6.15*	4.45		0.50 [†]	0.15	14

JEDEC Registration MO-220, Variation VJJD-6, Issue K, June 2006.

* This dimension is not specified in the JEDEC drawing.

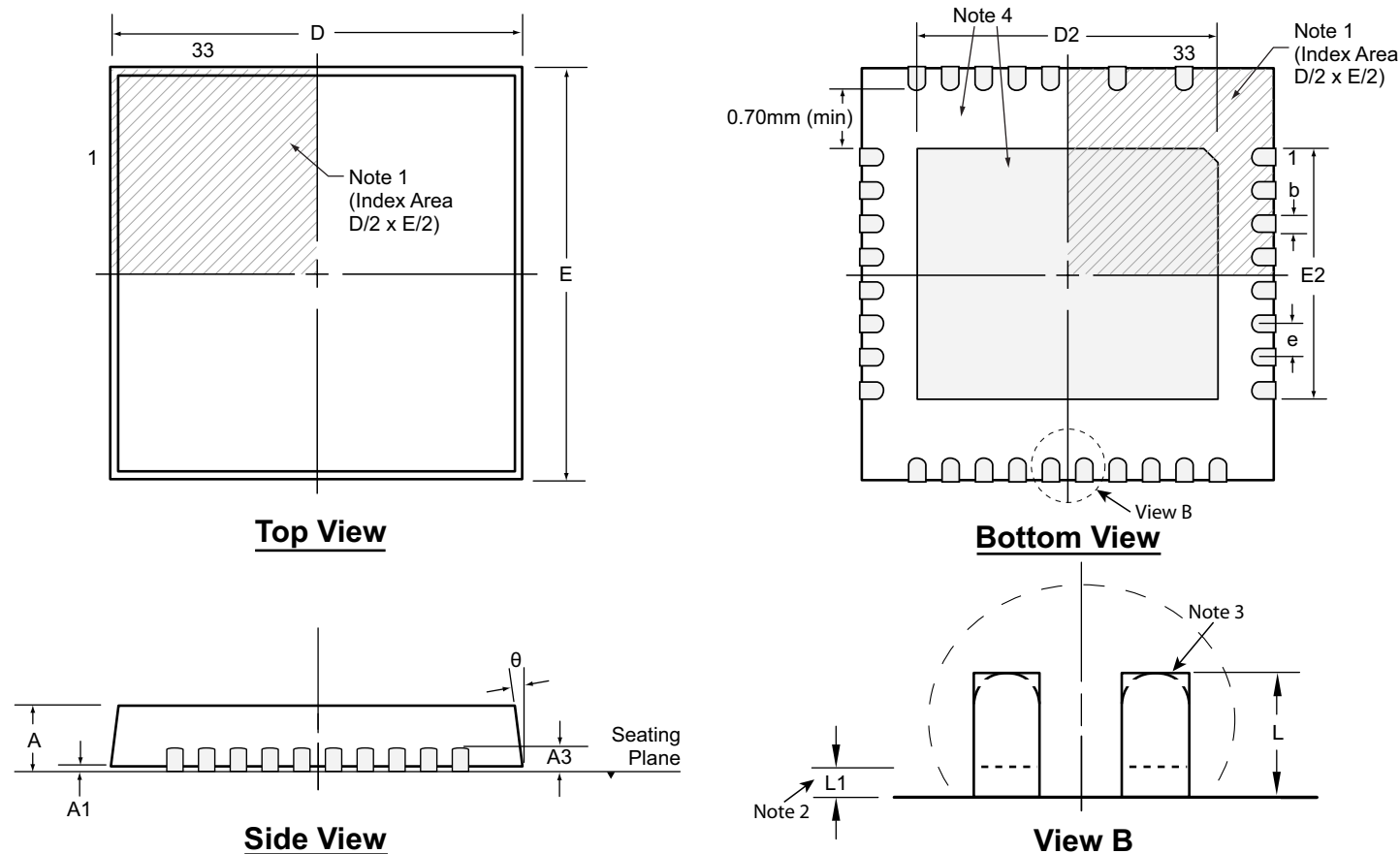
[†] This dimension differs from the JEDEC drawing.

Drawings not to scale.

Supertex Doc. #: DSPD-40QFNK66X6P050, Version C041009.

33-Lead QFN Package Outline (K63)

6.00x6.00mm body, 1.00mm height (max), 0.50mm pitch



Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.
3. The inner tip of the lead may be either rounded or square.
4. There will be an exposed DAP. A minimum of 0.7mm spacing will be maintained between the leads and the DAP.

Symbol		A	A1	A3	b	D	D2	E	E2	e	L	L1	θ°
Dimension (mm)	MIN	0.80	0.00	0.20 REF	0.18	5.85	4.00	5.85	3.60	0.50 BSC	0.30	0.00	0
	NOM	0.90	0.02		0.25	6.00	4.15	6.00	3.75		0.40	-	-
	MAX	1.00	0.05		0.30	6.15	4.25	6.15	3.85		0.50	0.15	14

Drawings not to scale.

Supertex Doc. #: DSPD-33QFNK636X6P050, Version A021312.

(The package drawings in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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